

# DA2J001 (Tentative)

Silicon epitaxial planar type

For band switching

## ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	35	V
Forward current	$I_F$	100	mA
Operating ambient temperature *	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: Maximum ambient temperature during operation.

## ■ Package

- Code  
SMini2-F5-B
- Pin Name  
1: Cathode  
2: Anode

## ■ Marking Symbol: D1

## ■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100\text{ mA}$			1.0	V
Reverse current	$I_R$	$V_R = 33\text{ V}$			100	nA
Diode capacitance	$C_D$	$V_R = 6\text{ V}, f = 1\text{ MHz}$			1.2	pF
Forward dynamic resistance *	$r_f$	$I_F = 2\text{ mA}, f = 100\text{ MHz}$			0.85	$\Omega$

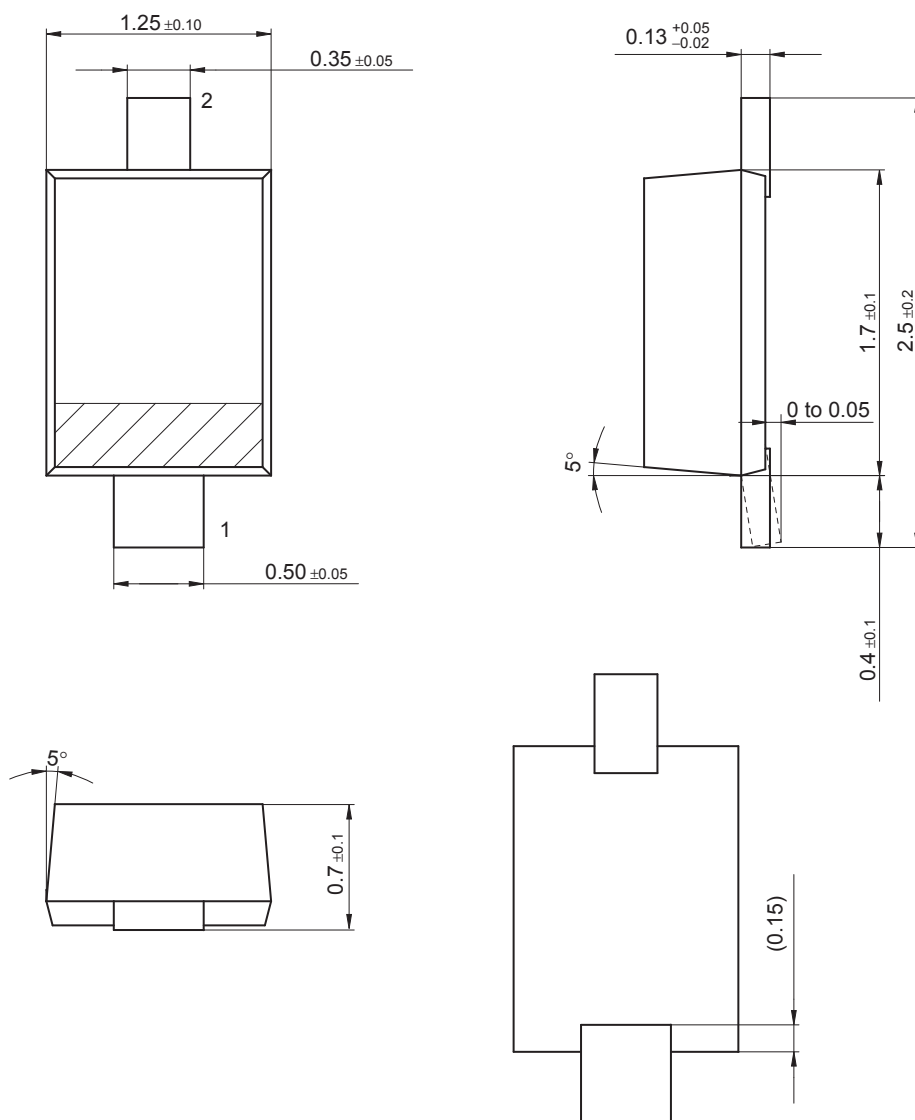
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

3. \*: Measuring instrument: YHP 4191A RF IMPEDANCE ANALYZER

# SMini2-F5-B

Unit: mm



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